

**Assembly Site Transfer of Select CSP\_BGA Products to STATS ChipPAC Korea**

**Qualification Results Summary  
for CSP\_BGA and BOM Change at STATS ChipPAC Korea**

<b>QUALIFICATION RESULT</b>			
<b>TEST</b>	<b>SPECIFICATION</b>	<b>SAMPLE SIZE</b>	<b>RESULTS</b>
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 32	PASS
Unbiased Highly Accelerated Stress Test (uHAST)*	JEDEC <i>JESD22-A118</i>	3 x 32	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	PASS
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1 x 32	PASS

\*Preconditioned per JEDEC/IPC J-STD-020

<b>FG_NAME</b>	<b>BodySize</b>	<b>PkgLeadCount</b>	<b>Wire Type(Before)</b>
<b>ADAS1131JBCZ</b>	<b>15X15_MM</b>	<b>324</b>	<b>Gold</b>
<b>ADAS1135JBCZ</b>	<b>15X15_MM</b>	<b>324</b>	<b>Gold</b>
<b>ADUCM310BBCZ</b>	<b>6X6_MM</b>	<b>112</b>	<b>Gold</b>
<b>ADUCM310BBCZ-RL</b>	<b>6X6_MM</b>	<b>112</b>	<b>Gold</b>
<b>ADUCM320BBCZI-RL</b>	<b>6X6_MM</b>	<b>96</b>	<b>Gold</b>
<b>ADUCM320BBCZ-RL</b>	<b>6X6_MM</b>	<b>96</b>	<b>Gold</b>
<b>ADUCM322BBCZ</b>	<b>6X6_MM</b>	<b>96</b>	<b>Gold</b>
<b>ADUCM322BBCZI</b>	<b>6X6_MM</b>	<b>96</b>	<b>Gold</b>
<b>ADUCM322BBCZI-RL</b>	<b>6X6_MM</b>	<b>96</b>	<b>Gold</b>
<b>ADUCM322BBCZ-RL</b>	<b>6X6_MM</b>	<b>96</b>	<b>Gold</b>
<b>ADUCM320BBCZ</b>	<b>6X6_MM</b>	<b>96</b>	<b>Gold</b>
<b>ADUCM320BBCZI</b>	<b>6X6_MM</b>	<b>96</b>	<b>Gold</b>



